L Number	Hits	Search Text	DB	Time stamp
239	1	((semiconductor r s mi$1conductor) n ar3 dynamic) with (adhesive near3 film)	USPAT; US-P PUB	2003/06/18 15:04
241	28	((semiconductor or semi$1conductor) n ar3 dynamic) and (adhesive near3 film)	USPAT; US-P PUB	2003/06/18 15:10
242	17	(dynamic near3 (sensor or detector)) and (adhesive near3 film)	USPAT; US-PGPUB	2003/06/18 15:30
243	7	(sensor near3 chip) with (adhesive near3 film)	USPAT; US-PGPUB	2003/06/18 15:56
244	7	("5266827" | "5656711" | "5747694" | "6034421" | "6040400" | "6121359" | "6127504").PN.	USPAT	2003/06/18 15:32
249	2	(sensor near3 chip) near5 (adhesive near3 film) near4 (substrate)	USPAT; US-PGPUB	2003/06/18 16:00
250	2	(sensor near3 chip) with ((adhesive near3 film) or (polymide near3 resin)) near4 (substrate)	USPAT; US-PGPUB	2003/06/18 16:01
251	5	(sensor near3 chip) with ((adhesive near3 film) or (polymide near3 resin))	EPO; JPO; DERWENT	2003/06/18 16:25
255	9	((sensor near3 chip) near3 (coupl$3 or attach$3 or connect$4 or laminat$3 or mount$3) near3 ((circuit near chip) or substrate)) and (adhesive near3 film)	USPAT; US-PGPUB	2003/06/18 16:41
256	47	((sensor near3 chip) same ((circuit near3 chip) or substrate)) and ((adhesive near3 film) or (polymide near3 resin))	USPAT; US-PGPUB	2003/06/18 17:12
257	4652	((circuit near3 chip) or substrate) with ((adhesive near3 film) or (polymide near3 resin))	USPAT; US-PGPUB	2003/06/18 17:14
258	937	(((circuit near3 chip) or substrate) near4 (mount$3 on attach$3 or connect$ or interpose$3 or laminat$3)) with ((adhesive near3 film) or (polymide near3 resin))	USPAT; US-PGPUB	2003/06/18 17:19
260	1	(((circuit near3 chip) or substrate) with ((adhesive near3 film) or (polymide near3 resin))) same (dynamic near3 sensor)	USPAT; US-PGPUB	2003/06/18 17:22
259	8	(((circuit near3 chip) or substrate) with ((adhesive near3 film) or (polymide near3 resin))) same (acceleration)	USPAT; US-PGPUB	2003/06/18 17:22
261	2	(((((circuit near3 chip) or substrate) near4 (mount$3 on attach$3 or connect$ or interpose$3 or laminat$3)) with ((adhesive near3 film) or (polymide near3 resin))) same (acceleration)	USPAT; US-PGPUB	2003/06/18 17:23
262	2	(((((circuit near3 chip) or substrate) near4 (mount$3 on attach$3 or connect$ or interp se$3 or laminat$3)) with ((adhesive near3 film) r (polymid near3 resin))) same (sensor near3 chip)	USPAT; US-PGPUB	2003/06/18 17:24

263	10	((sensor near3 chip) n ar3 (coupl$3 or attach$3 or connect$4 or laminat$3 or mount$3) near3 ((circuit near3 chip) or substrat)) and (adhesive near3 film)	USPAT; US-P PUB	2003/06/18 17:28
264	11	((sensor near3 chip) near3 (coupl$3 or attach$3 or connect$4 or laminat$3 or mount$3) near3 ((circuit near3 chip) or substrate)) and ((adhesive near3 film) or polyimide near3 adhesive)	USPAT; US-PGPUB	2003/06/18 18:04
265	0	(stack$3 near3 microchip) with ((adhesive near3 film) or (polyimide near3 adhesive))	USPAT; US-PGPUB	2003/06/18 18:05
266	5	(stack$3 near3 microchip) and ((adhesive near3 film) or (polyimide near3 adhesive))	USPAT; US-PGPUB	2003/06/18 18:07
267	30	(stack$3 near3 microchip) and ((adhesive near3 film) or ((polyimide or polymer) near3 (adhesive or film)))	USPAT; US-PGPUB	2003/06/18 18:09